

500mA Variable/Fixed Output LDO Regulators



BDxxKA5 Series BDxxKA5W Series **BD00KA5W Series**

General Description

The BDxxKA5 series are low-saturation regulators that are available for output currents up to 500mA. The output voltage precision is ±1%. These LDO regulators are offered in several output voltages and package lineups with or without ON/OFF switches (that set the circuit current to 0µA at shutdown). This series can be used for a broad spectrum of applications ranging from TVs and car audio systems to HDDs, PCs, and DVDs. There regulators have a built-in overcurrent protection circuit that prevents the destruction of the IC, due to output short circuits and a thermal shutdown circuit.

Features

- Output voltage precision: ±1%
- Low-saturation voltage with PMOS output: 0.12V Typ.(Io=200mA)
- Built-in over-current protection circuit
- Built-in thermal shutdown circuit
- Shutdown switch (BDxxKA5WFP and BDxxKA5WF series)
- Ceramic capacitor compatible (recommended capacitance: 1µF or greater)

Key Specifications

- Input Power Supply Voltage:
- Output voltage type: BA00KA5

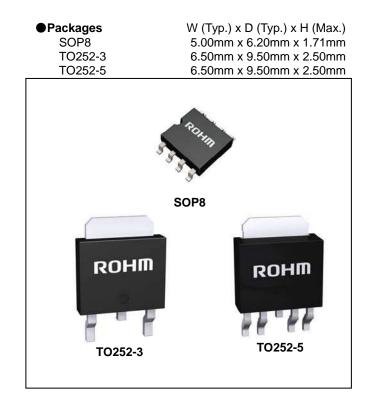
Variable BAxxKA5 Fixed

Output current:

500mA (Max.) -40°C to +105°C Operating temperature range:

Applications

Microcontrollers and all electronic devices that use logic circuit



Lineup matrix

Part Number			Package						
	1.0	1.2	1.5	1.8	2.5	3.0	3.3	Variable	T donago
BDxxKA5WFP	0	0	0	0	0	0	0	0	TO252-5
BDxxKA5WF	0	0	0	0	0	0	0	0	SOP8
BDxxKA5FP	0	0	0	0	0	0	0	_	TO252-3

5.5V (Max.)

Ordering Information

E	3	D	Х	Х	K	А	5	W	Х	Х	-	E 2	
Pa	rt Nu		Output 00:Varia Other: F		Curren KA5: 5	t capacity 00mA	W:	utdown Switch Include ne:without	FP : TC)252-3)252-5		Packaging and fo E2: Embossed tap	rming specification pe and reel

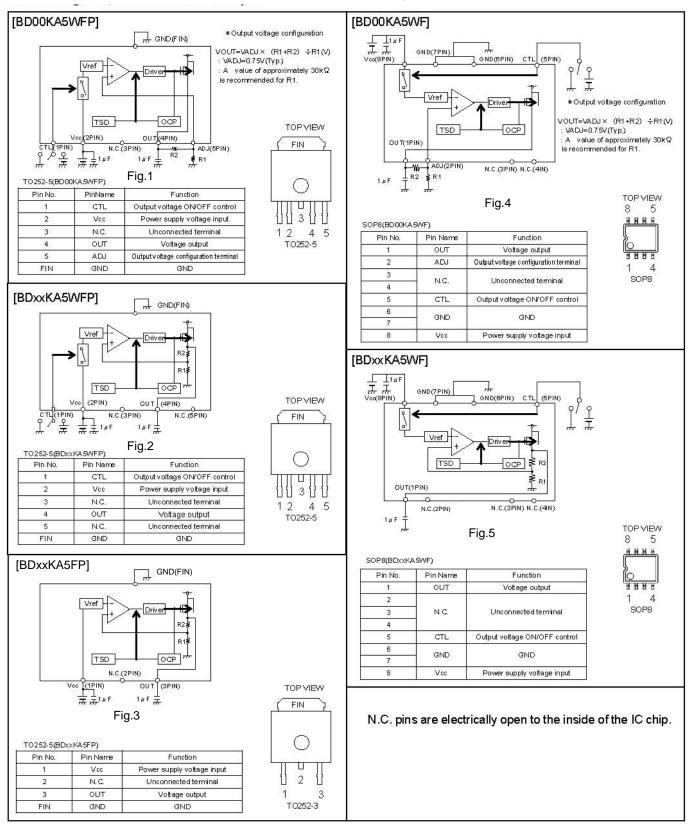
OProduct structure : Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays.

BDxxKA5 Series BDxxKA5W Series BD00KA5W Series

•	Lineup

Maximum output current (Max.)	Shutdown Switch	Package		Output voltage (Typ.)	Orderable Part Number
				1.0V	BD10KA5WFP-E2
				1.2V	BD12KA5WFP-E2
				1.5V	BD15KA5WFP-E2
		TO252-5	Reel of 2000	1.8V	BD18KA5WFP-E2
		10252-5	Reel 01 2000	2.5V	BD25KA5WFP-E2
				3.0V	BD30KA5WFP-E2
				3.3V	BD33KA5WFP-E2
	With Switch			Variable	BD00KA5WFP-E2
			Reel of 2500	1.0V	BD10KA5WF-E2
				1.2V	BD12KA5WF-E2
				1.5V	BD15KA5WF-E2
500mA		SOP8		1.8V	BD18KA5WF-E2
		3060		2.5V	BD25KA5WF-E2
				3.0V	BD30KA5WF-E2
				3.3V	BD33KA5WF-E2
				Variable	BD00KA5WF-E2
				1.0V	BD10KA5FP-E2
				1.2V	BD12KA5FP-E2
				1.5V	BD15KA5FP-E2
	No Switch	TO252-3	Reel of 2000	1.8V	BD18KA5FP-E2
				2.5V	BD25KA5FP-E2
				3.0V	BD30KA5FP-E2
				3.3V	BD33KA5FP-E2

Block Diagrams / Standard Example Application Circuits / Pin Configurations / Pin Descriptions



Absolute Maximum Ratings (Ta=25°C)

Param	eter	Symbol	Limits	Unit.
Power Supply Volta	ge	Vcc	-0.3 to +7.0 ^{*1}	V
Output Control Tern	ninal Voltage	VCTL	-0.3 to Vcc ^{*1}	V
	TO252-3		1200 ^{*2}	
Power Dissipation	TO252-5	Pd	1300 ^{*3}	mW
	SOP8		687.6 ^{*4}	
Operating Temperature Range		Topr	-40 to +105	°C
Ambient Storage Te	emperature	Tstg	-55 to +150	°C
Maximum Junction	Temperature	Tjmax	150	°C

*1 Must not exceed Pd

*2 When a 70mm×70mm×1.6mm glass epoxy board is used. Reduce by 9.6 mW/°C over 25°C.
*3 When a 70mm×70mm×1.6mm glass epoxy board is used. Reduce by 10.4mW/°C over 25°C.
*4 When a 70mm×70mm×1.6mm glass epoxy board is used. Reduce by 5.5 mW/°C over 25°C.

Recommended Operating Ratings (Ta=25°C)

Parameter	Symbol	Min.	Max.	Unit.
Input Power Supply Voltage	Vcc	2.3	5.5	V
Output Current	lo	0	500	mA
Output Voltage Configuration Range ^{*5}	Vo	1.0	4.0	V
Output Control Terminal Voltage	VCTL	0	Vcc	V

*5 Only BD00KA5WFP and BD00KA5WF

• Electrical Characteristics

BDxxKA5 Series BDxxKA5W Series

 $(Unless otherwise specified, Ta=25^{\circ}C, VCTL=2V, Vcc=2.5V(Vo=1.0V, 1.2V, 1.5V, 1.8V), Vcc=3.3V(Vo=2.5V), Vcc=5.0V(Vo=3.0V, 3.3V))$

Parameter	Symbol		Limit	-	Unit	Conditions	
Falamelei	Symbol	Min Typ Max		Unit	Conditions		
	Vo	Vo(T)-0.015	Vo(T)	Vo(T)+0.015	V	Io=200mA (Vo=1.0V,1.2V)	
Output Voltage	VU	Vo(T) × 0.99	Vo(T)	Vo(T) × 1.01	v	lo=200mA (Vo≧1.5V)	
Shut Down Current	lsd		0	1	μA	VCTL=0V, Io=0mA (OFFmode)	
Bias Current	lb	_	350	550	μA	lo=0mA	
Dropout Voltage *6	$\Delta V d$	—	0.12	0.20	V	Io=200mA, Vcc=0.95 × Vo	
Peak Output Current	lo	500	_	—	mA		
Ripple Rejection	R.R.	_	50	_	dB	f=120Hz, ein ^{※9} =-10dBV, Io=100mA	
Line Regulation *7	Reg.I	_	10	35	mV	Vcc=Vo+0.5V→5.5V, Io=200mA	
Load Regulation	Reg.L	_	25	75	mV	Io=0mA→500mA	
Temperature Coefficient of Output Voltage *8	Тсvо	_	±100	_	ppm/°C	lo=5mA,Tj=0 to 125°C	
CTL ON Mode Voltage	VCTLON	2.0		-	V	ACTIVE MODE, Io=0mA	
CTL OFF Mode Voltage	VCTLOFF	_	_	0.8	V	OFF MODE, Io=0mA	
CTL Input Current	ICTL	20	40	60	μA	Io=0mA	

Vo(T) : Output Voltage

Vo≧2.5V *7

1.0≦Vo≦1.8V,Vcc=2.3V→5.5V

*8 Not 100% tested

*9 ein : Input Voltage Ripple

Electrical Characteristics – continued

BD00KA5W Series

(Unless otherwise specified, Ta=25°C, Vcc=2.5V, V_{CTL}=2V ,Vo=1.5V)

Parameter	Symbol	Limit			Unit	Conditions	
Parameter	Symbol	Min	Тур	Max	Unit	Conditions	
Shut Down Current	lsd		0	1	μA	VCTL=0V, Io=0mA (OFFmode)	
Bias Current	lb		350	550	μA	Io=0mA	
Reference Voltage	Vadj	0.742	0.750	0.758	V	Io=50mA	
Dropout Voltage *10	$\Delta V d$	1	0.12	0.20	V	Io=200mA, Vcc=0.95 × Vo	
Peak Output Current	lo	500	1	—	mA		
Ripple Rejection	R.R.	1	50	—	dB	f=120Hz, ein ^{%12} =-10dBV, lo=100mA	
Line Regulation	Reg.I	1	10	35	mV	Vcc=Vo+0.5V→5.5V, Io=200mA	
Load Regulation	Reg.L	-	25	75	mV	Io=0mA→500mA	
Temperature Coefficient of Output Voltage *11	Тсvо		±100	_	ppm/°C	lo=5mA,Tj=0 to 125°C	
CTL ON Mode Voltage	VCTLON	2.0	-	—	V	ACTIVE MODE, Io=0mA	
CTL OFF Mode Voltage	VCTLOFF	_	_	0.8	V	OFF MODE, Io=0mA	
CTL Input Current	ICTL	20	40	60	μA	Io=0mA	

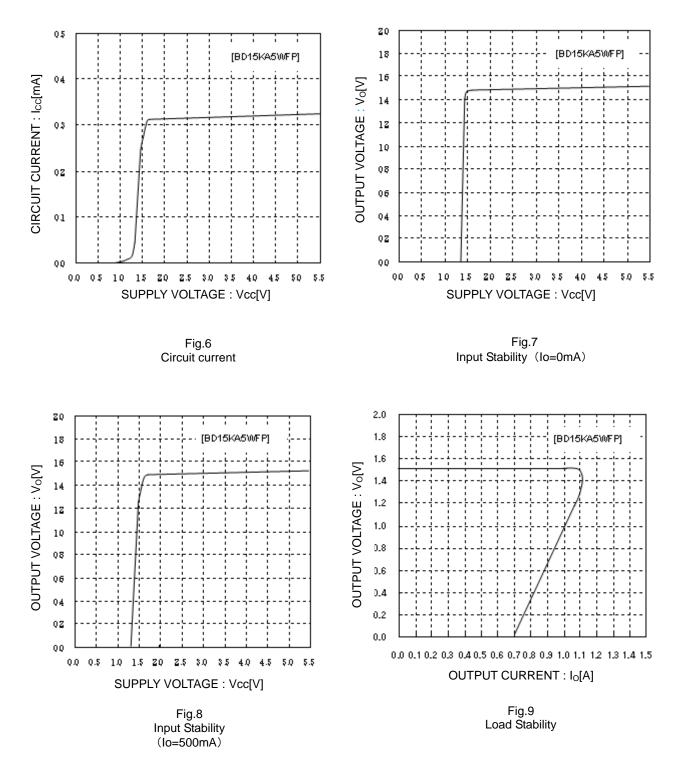
*¹⁰ Vo≧2.5V

*¹¹ Not 100% tested

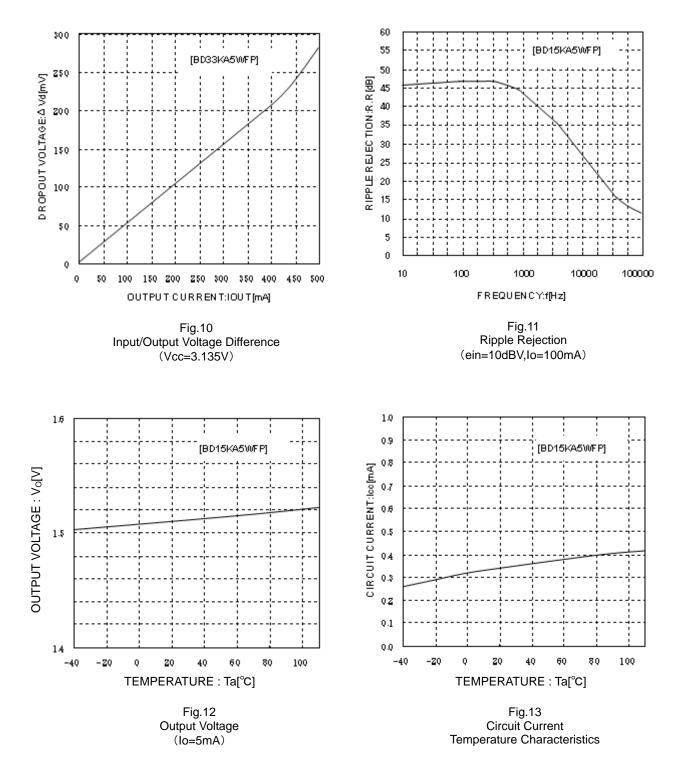
*¹² ein : Input Voltage Ripple

Typical Performance Curves

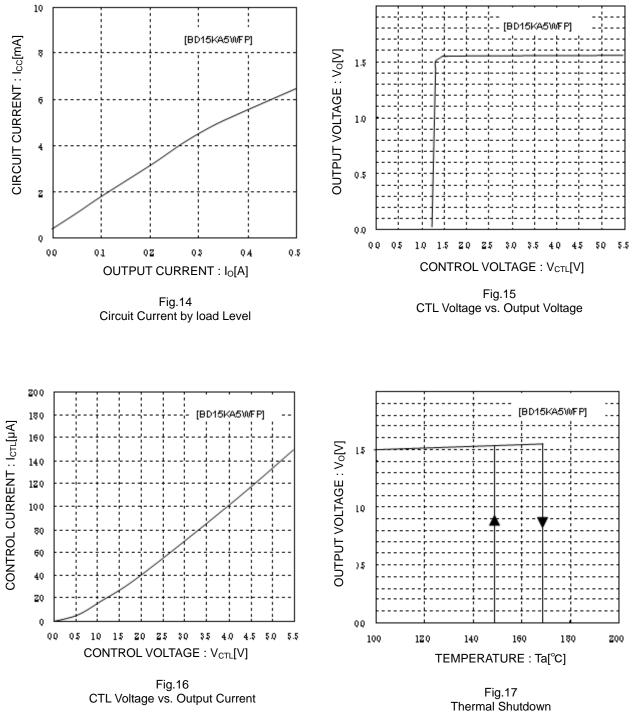
(Unless specified otherwise, Vcc=25V,V_{CTL} =2V,and Io=0mA)



Typical Performance Curves - continued

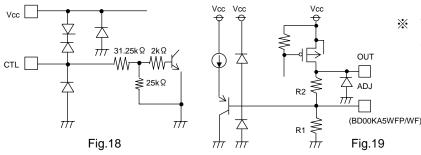


Typical Performance Curves - continued



Circuit Characteristics (Io=5mA)

●I/O equivalence circuit



With BD00KA5WFP/WF,R1and R2 are connected outside the IC between ADJ and GND and between OUT and ADJ.

TO252-3

θ ia=104.2(℃/W)

75

Fig.21 Power Dissipation heat

reducing characteristics

Ambient temperature : Ta(°C)

100

125

150

Rohm standard board mounting

Board size : 70×70×1.6mm

Copper foil area : $7 \times 7 \text{ mm}^2$

2.0

1.6

1.2

0.8

0.4

0.0

0

1.20

25

50

Power Dissipation : Pd(W)

Power Dissipation

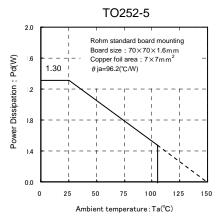
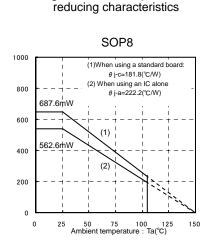
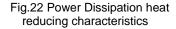


Fig.20 Power Dissipation heat reducing characteristics





When using at temperatures over Ta=25°C, please refer to the power dissipation shown in Fig.20 through 22.

The IC characteristics are closely related to the temperature at which the IC is used, so if the temperature exceeds the maximum junction temperature TjMAX, the device may malfunction or be destroyed. The heat of the IC requires sufficient consideration regarding instantaneous destruction and long-term operation reliability. In order to protect the IC from thermal damage, it is necessary to operate it at temperatures less than the maximum junction temperature TjMAX. Even when the ambient temperature Ta is a normal temperature (25°C), the chip(junction) temperature Tj may be quite high,

Even when the ambient temperature I a is a normal temperature (25°C), the chip(junction) temperature I j may be quite high, so please operate the IC at temperatures less than the acceptable loss Pd.

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Power Dissipation : Pd(W)

The calculation method for power consumption Pc(W) is as follows :

 $Pc = (Vcc-Vo) \times Io + Vcc \times Icca$ Acceptable loss $Pd \ge Pc$

Solving for the load current I_0 in order to operate within the acceptable loss,

 $lo \leq \frac{Pc - Vcc \times lcca}{Vcc - Vo}$

It is then possible to find the maximum load current IOMAX with respect to the applied voltage Vcc at the time of thermal design.

Calculation Example

Example 1) When Ta=85°C, Vcc=2.5V, Vo=1.0V

· , , , , ,	BA10KA5WFP (TO252-5 packaging)
$lo \le \frac{0.676 - 2.5 \times lcca}{2.5 - 1.0}$	θ ja=96.2°C/W \rightarrow -10.4mW/°C
lo≦440mA (lcca : 6mA)	$25^{\circ}C=1300$ mW $\rightarrow 85^{\circ}C=676$ mW

Please refer to the above information and keep thermal designs within the scope of acceptable loss for all operating temperature ranges.

The power consumption Pc of the IC when there is a short circuit (short between Vo and GND) is :

Pc=Vccx(lcca+lshort)

*Ishort : Short circuit current

Terminal Vicinity Settings and Cautions

Vcc Terminal

Please attach a capacitor (greater than 1μ F) between Vcc and GND.

The capacitance values differ depending on the application, so chose a capacitor with sufficient margin and verify the operation on actual board.

GND Terminal

Please be sure to keep the set ground and IC ground at the same potential level so that a potential difference does not arise between them. If a potential difference arises between the set ground and the IC ground, the preset voltage will not be output properly, causing the system to become unstable. Please reduce the impedance by making the ground patterns as wide as possible and reducing the distance between the set ground and the IC ground as much as possible.

CTL Terminal

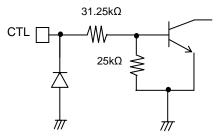
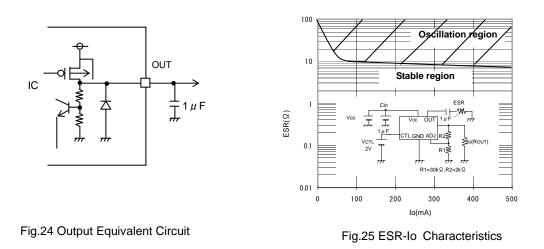


Fig.23 Input equivalent circuit

The CTL terminal is turned ON at 2.0V and higher, and OFF at 0.8V and lower, within the operating power supply voltage range. The power supply and the CTL terminal may be started up and shut down in any order without problems.

●Vo Terminal

Please be sure to attach an anti-oscillation capacitor between Vo and GND.



Be sure to place an anti-oscillation capacitor between the output terminal and the GND. Oscillations may arise if the capacitance value changes, due to factors such as temperature changes. A 1μ F capacitor with small internal series resistance (ESR) such as a ceramic capacitor is recommended as an anti-oscillation capacitor. Ceramic capacitors generally have favorable temperature characteristics and DC bypass characteristics. When selecting a ceramic capacitor, a high voltage capacitor (good DC bypass characteristics) with temperature characteristics that are superior to those of X5R or X7R, is recommended. In applications where input voltage and load fluctuations are rapid, please decide on a capacitor after sufficiently confirming its properties according to its specifications in the actual application.

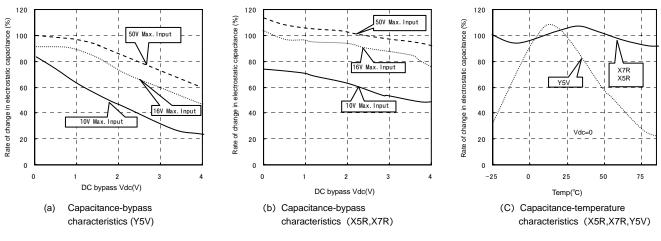


Fig.26 General characteristics of ceramic capacitors

Operational Notes

OProtection Circuits

Over-current Protection Circuit

A built-in over-current protection circuit corresponding to the current capacity prevents the destruction of the IC when there are load shorts. This protection circuit is a "7"-shaped current control circuit that is designed such that the current is restricted and does not latch even when a large current momentarily flows through the system with a high-capacitance capacitor. However, while this protection circuit is effective for the prevention of destruction due to unexpected accidents, it is not suitable for continuous operation or transient use. Please be aware when creating thermal designs that the over-current protection circuit has negative current capacity characteristics with regard to temperature.

OThermal Shutdown Circuit (Thermal Protection)

This system has a built-in temperature protection circuit for the purpose of protecting the IC from thermal damage. As shown in Fig. 20-22, this must be used within the range of acceptable loss, but if the acceptable loss is continuously exceeded, the chip temperature Tj increases, causing the thermal shutdown circuit to operate. When the thermal shutdown circuit operates, the operation of the circuit is suspended. The circuit resumes operation immediately after the chip temperature Tj decreases, so the output repeats the ON and OFF states (Please refer to Fig.17 for the temperatures at which the temperature protection circuit operates).

There are cases in which the IC is destroyed due to thermal runaway when it is left in the overloaded state. Be sure to avoid leaving the IC in the overloaded state.

OReverse Current

In order to prevent the destruction of the IC when a reverse current flows through the IC, it is recommended that a diode be placed between the Vcc and Vo and a pathway be created so that the current can escape (Refer to Fig.27).

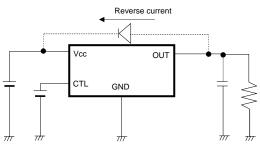


Fig.27 Bypass diode

OThis IC is BI-CMOS IC that has a P-board (substrate) and P+ isolation between each element, as shown in Fig.28. A P-N junction is formed between this P-layer and the N-layer of each element, and the P-N junction operates as :

- a parasitic diode when the electric potential relationship is GND> Pin A, GND> Pin B, or
- a parasitic transistor when the electric potential relationship is Pin B > GND> Pin A.

Parasitic elements are structurally inevitable in the IC. The operation of parasitic elements induces mutual interference between circuits, causing malfunctions and eventually the destruction of the IC. Take precaution as not to use the IC in ways that would cause parasitic elements to operate. For example, applying a voltage that is lower than the GND (P-board) to the input terminal.

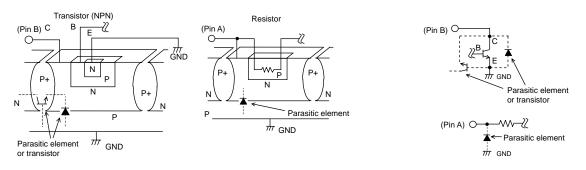


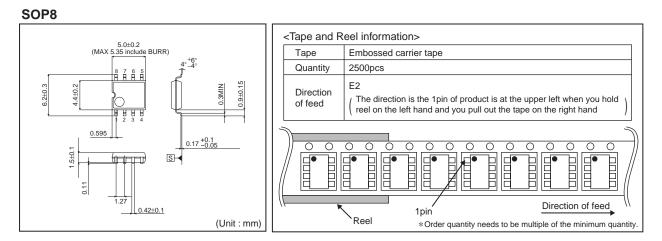
Fig.28 Basic structure example

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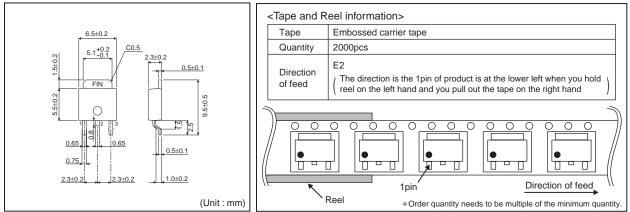
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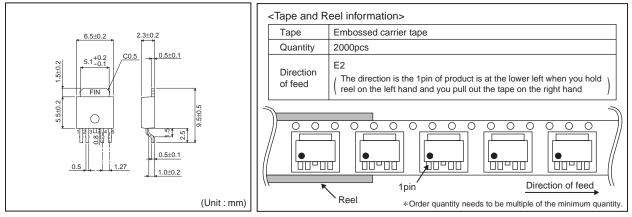
Physical Dimension Tape and Reel Information



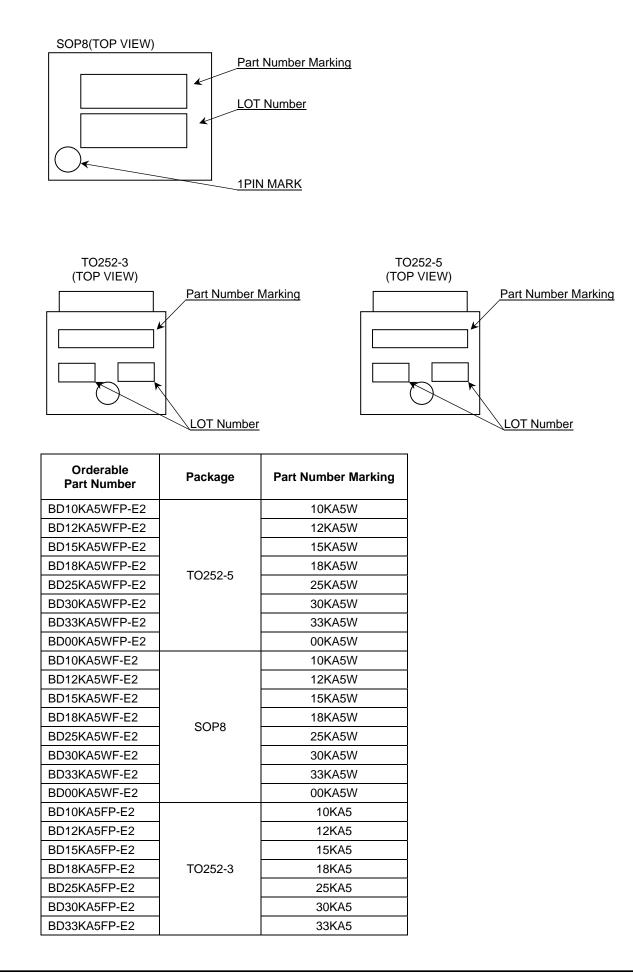
TO252-3



TO252-5



Marking Diagrams



BDxxKA5 Series BDxxKA5W Series BD00KA5W Series

Revision History

Date	Revision	Changes
26.Jun.2012	001	New Release

Notice

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA	
CLASSⅢ	CLASSⅢ	CLASS II b		
CLASSⅣ	CLASSIII	CLASSⅢ	CLASSⅢ	

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 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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